

规格书编号

SPEC NO:

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF703E-F11 _____

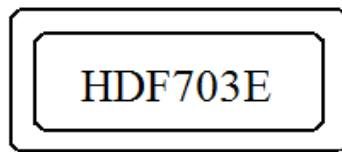
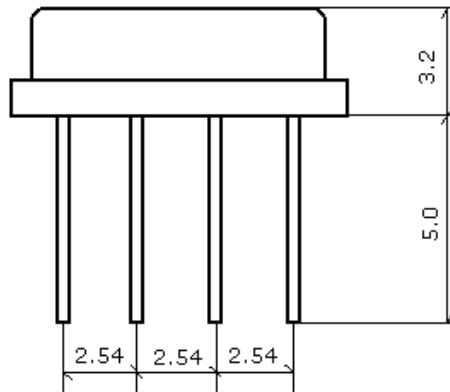
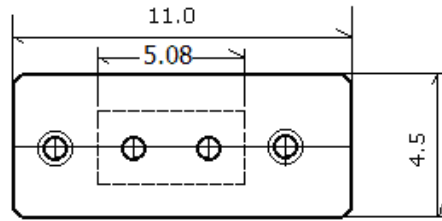
PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ D A T E 日期: _____ 2013-9-16 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension

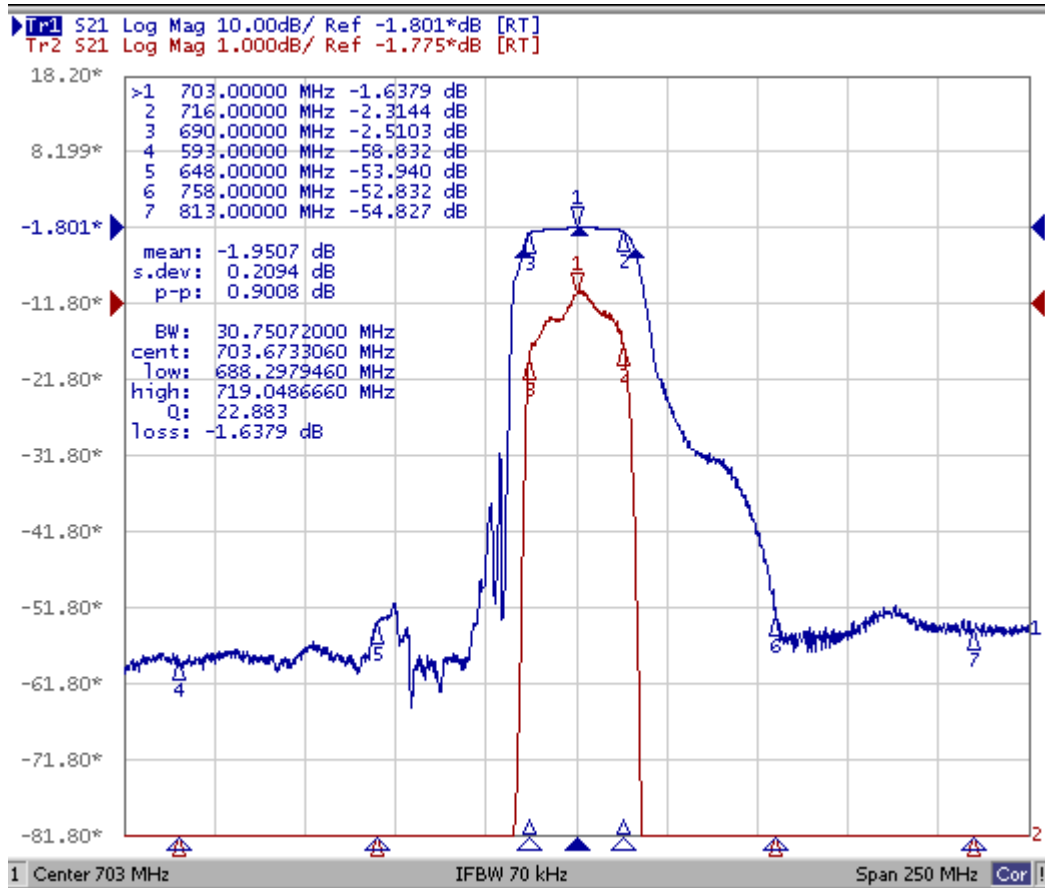


2. Maximum Rating

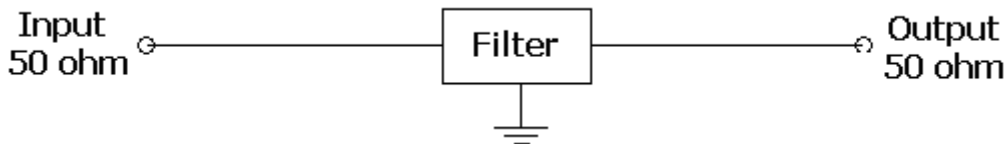
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
Maximum DC Voltage	10 V
Maximum Input Power	10 dBm

3. Performance

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	703	-
Insertion Loss (Fc ± 13 MHz)	dB		2.2	4.0
Amplitude Ripple(Fc ± 13 MHz)	dB		0.8	2.0
VSWR (Fc ± 13 MHz)			1.8	2.5
Attenuation				
DC~ Fc-110 MHz	dB	40	50	-
Fc-110~ Fc-55 MHz		40	46	
Fc+55~ Fc+110 MHz		25	55	
Fc+110~1500 MHz		40	50	
Input/Output Impedance	Ohms		50	



Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -45°C for 30 minutes. Following by a high temperature of +25°C for 5 Minutes and a higher temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ±5°C for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the

specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.